

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

TSAI et al.

Group Art Unit:

Serial No. Not Yet Assigned

Examiner:

Filed: Concurrently Herewith

For: Method For Forming UBM Pads And Bumps On Wafer

INFORMATION DISCLOSURE STATEMENT

Honorable Assistant Commissioner for Patents
Washington, DC 20231

Sir:

In compliance with the duty of disclosure under 37 CFR 1.56, and 37 CFR 1.97-1.98, submitted herewith is two (2) copies of references, of which Applicants are aware, and which the Examiner may deem to be material or relevant to the examination of this application.

Without any assertion of prior art effect, the document is noted on the attached List of Documents, for the convenience of the Examiner. The Examiner is urged to make his or her own determination as to the relevance of this document.

Early action on the merits of the application is earnestly solicited.

Respectfully submitted,

Dennison, Schultz & Dougherty

Date: November 19, 2003

By: Malcolm J. MacDonald
Malcolm J. MacDonald
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Form PTO-1449	ATTY DOCKET NO. 3183/49	APPLICATION NO. N/A
INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)	APPLICANT TSAI et al.	
	FILING DATE Concurrently Herewith	GROUP

U. S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

EXAMINER _____ DATE CONSIDERED _____
EXAMINER: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.